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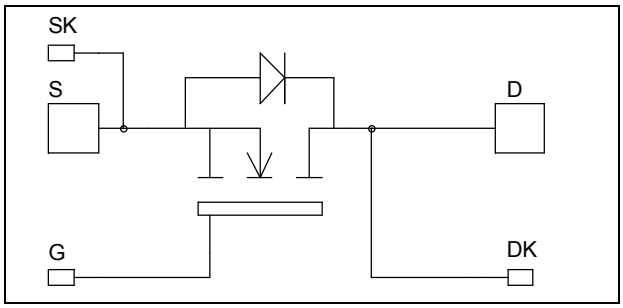
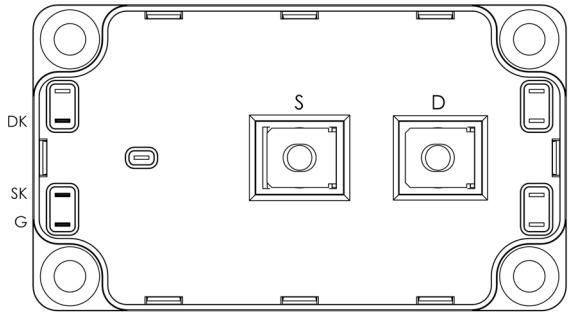
APTM20UM03FAG

Single Switch MOSFET Power Module

V_{DSS} = 200V
R_{DSon} = 3mΩ typ @ Tj = 25°C
I_D = 580A @ Tc = 25°C





Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Power MOS 7® FREDFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Fast intrinsic reverse diode
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration
- AlN substrate for improved thermal performance

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		200	V
I_D	Continuous Drain Current	T_c = 25°C	580	A
		T_c = 80°C	434	
I_{DM}	Pulsed Drain current		2320	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		3.6	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	2270	W
I_{AR}	Avalanche current (repetitive and non repetitive)		100	A
E_{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		3000	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS} = 200V	T_j = 25°C			500	µA
		V_{GS} = 0V, V_{DS} = 160V	T_j = 125°C			3000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 290A			3	3.6	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 15mA		3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V				±400	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		43.3		nF
C_{oss}	Output Capacitance			13.9		
C_{rss}	Reverse Transfer Capacitance			0.87		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 100V I_D = 580A		840		nC
Q_{gs}	Gate – Source Charge			318		
Q_{gd}	Gate – Drain Charge			402		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 133V I_D = 580A R_G = 0.8Ω		32		ns
T_r	Rise Time			64		
$T_{d(off)}$	Turn-off Delay Time			88		
T_f	Fall Time			116		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 580A, R_G = 0.8Ω		5		mJ
E_{off}	Turn-off Switching Energy			5.6		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 580A, R_G = 0.8Ω		5.6		mJ
E_{off}	Turn-off Switching Energy			5.9		

Source - Drain diode ratings and characteristics

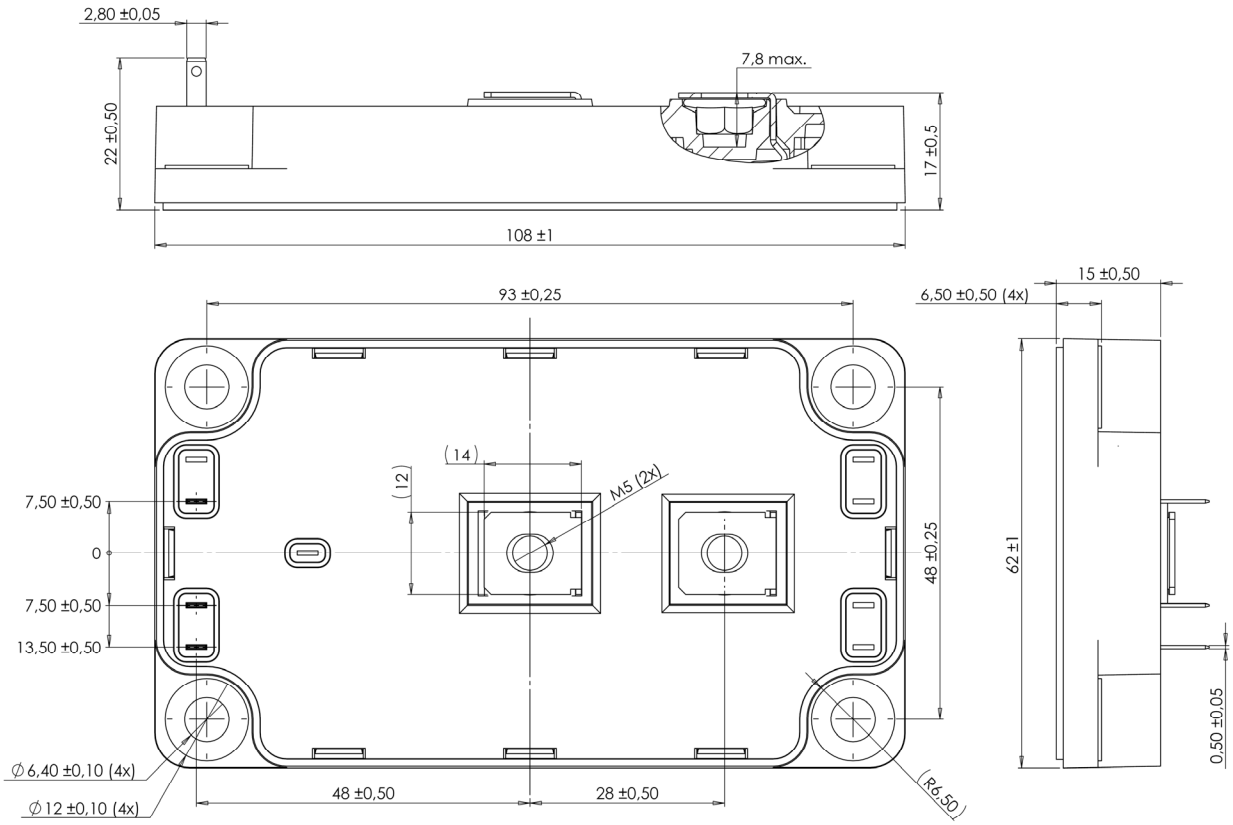
Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_S	Continuous Source current (Body diode)		Tc = 25°C			580	A
			Tc = 80°C			434	
V_{SD}	Diode Forward Voltage	V_{GS} = 0V, I_S = - 580A				1.3	V
dv/dt	Peak Diode Recovery ❶					8	V/ns
t_{rr}	Reverse Recovery Time	I_S = - 580A V_R = 500V di_S/dt = 600A/µs	T_j = 25°C			230	ns
			T_j = 125°C			450	
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		5.4		µC
			T_j = 125°C		20.4		

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.
$I_S \le$ - 580A di/dt ≤ 700A/µs $V_R \le V_{DSS}$ $T_j \le$ 150°C

Thermal and package characteristics

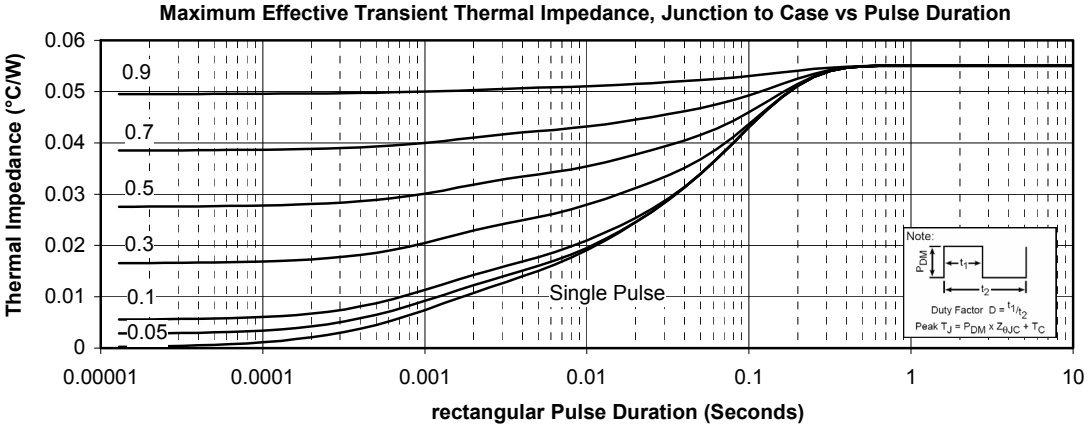
Symbol	*Characteristic*			*Min*	*Typ*	*Max*	*Unit*
R_{thJC}	Junction to Case Thermal Resistance					0.055	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

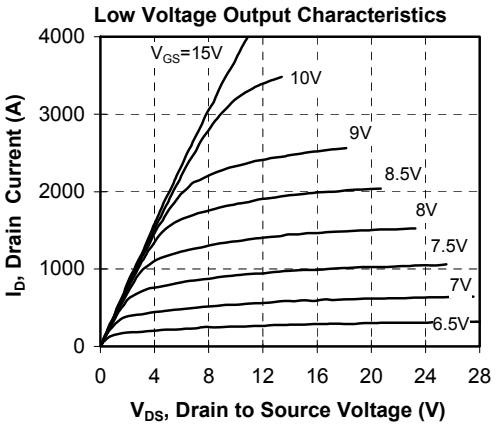
SP6 Package outline (dimensions in mm)

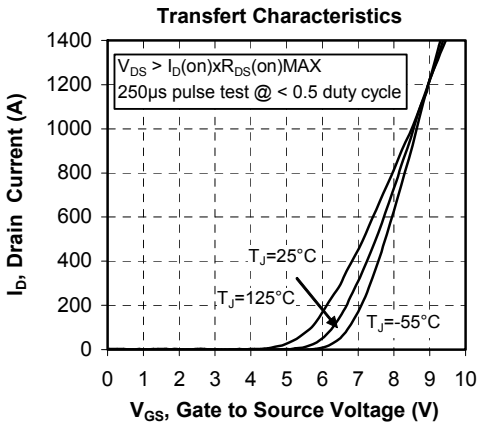


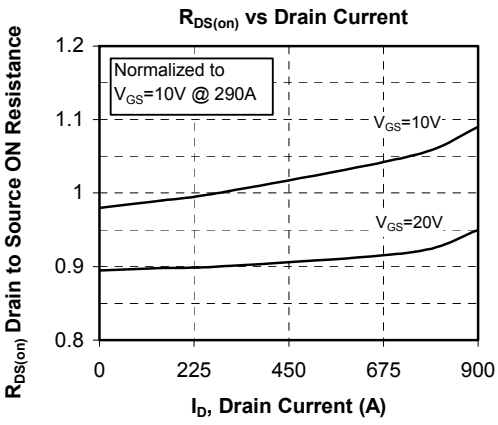
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

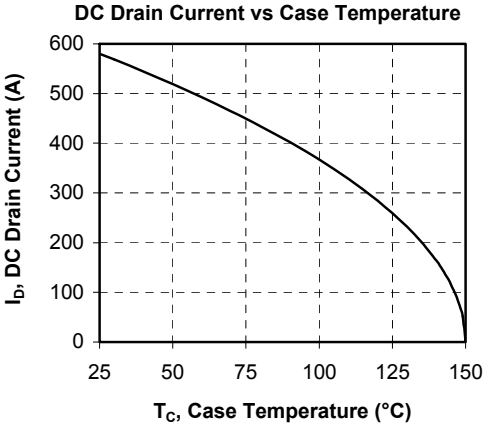
Typical Performance Curve



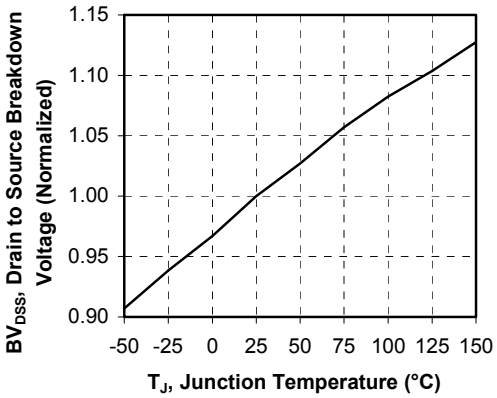




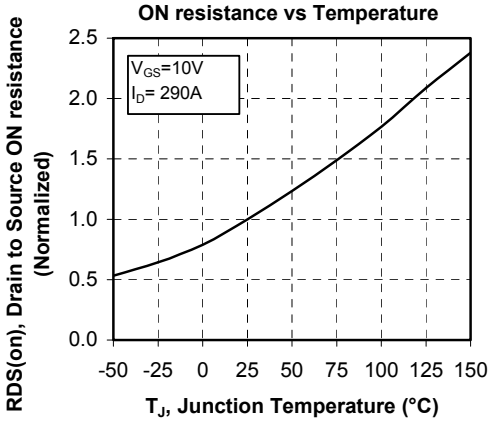




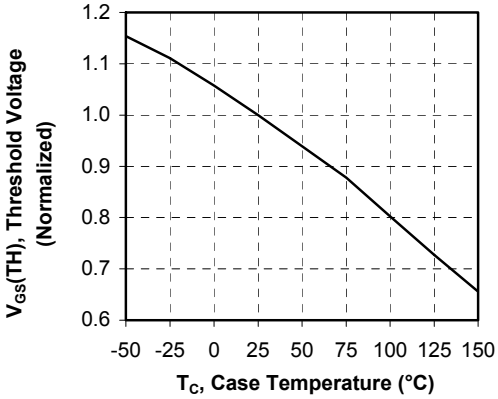
Breakdown Voltage vs Temperature



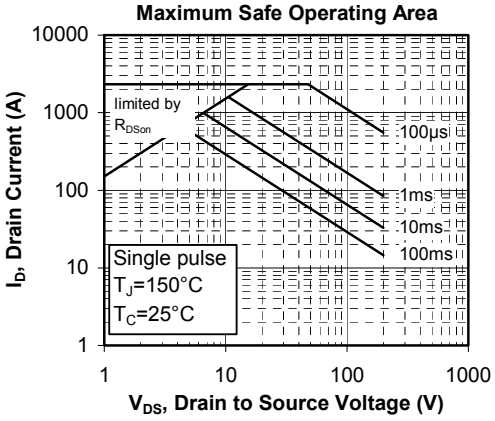
ON resistance vs Temperature



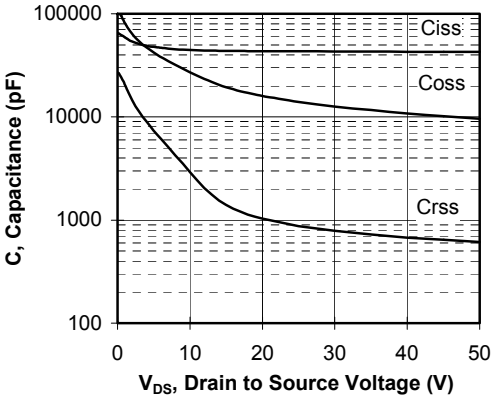
Threshold Voltage vs Temperature



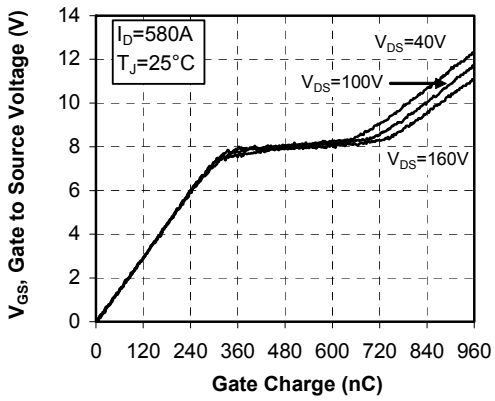
Maximum Safe Operating Area



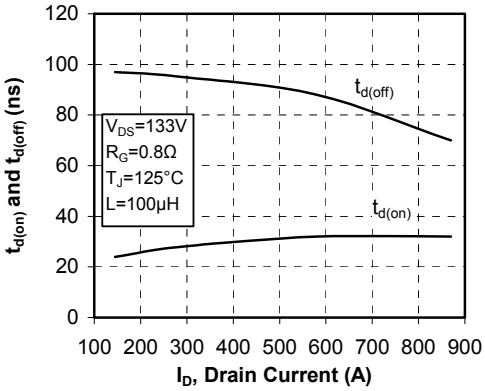
Capacitance vs Drain to Source Voltage



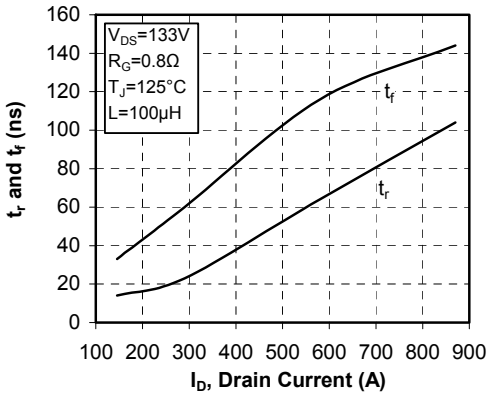
Gate Charge vs Gate to Source Voltage



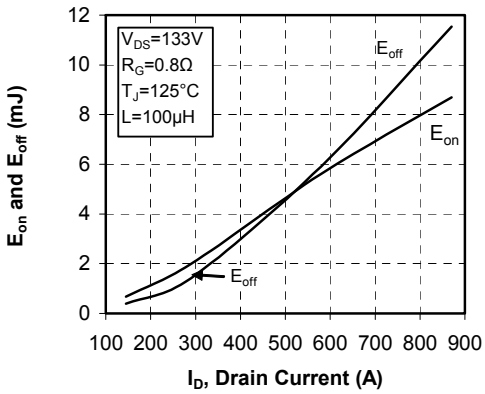
Delay Times vs Current



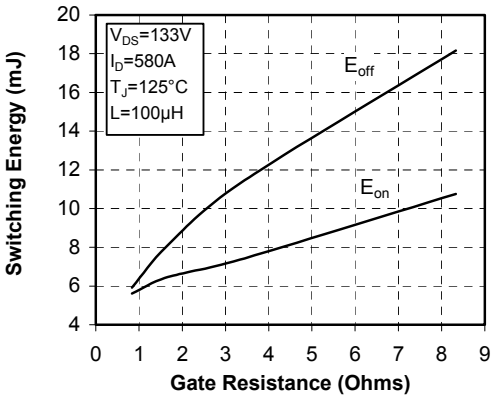
Rise and Fall times vs Current



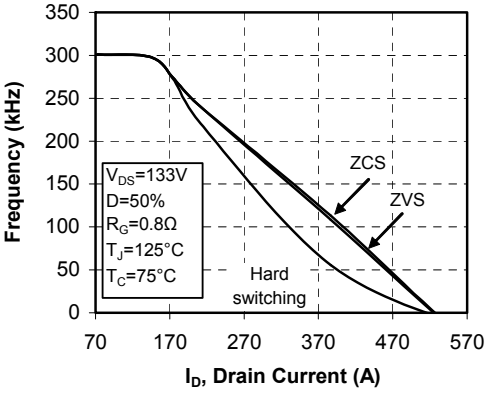
Switching Energy vs Current



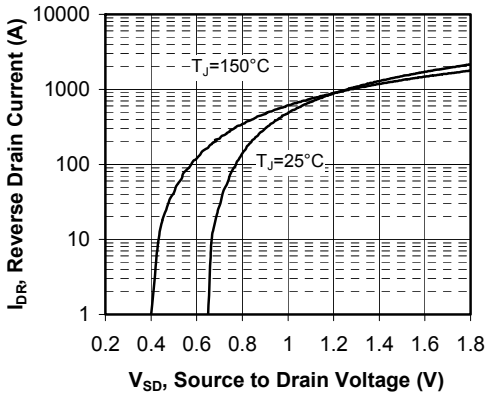
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



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